## Materials Declaration

### Molding Compound

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Other inorganic materials</td>
<td>Silica</td>
<td>8007-68-6</td>
<td>4.42E-02</td>
<td>39.5% 950000</td>
<td>36.1% 1680000</td>
</tr>
<tr>
<td>Thermosets</td>
<td>Epoxy &amp; Phenol Resin</td>
<td>Proprietary</td>
<td>6.47E-03</td>
<td>12.78 1278000</td>
<td>7.12 71212</td>
</tr>
<tr>
<td>Other inorganic materials</td>
<td>Carbon black</td>
<td>1333-86-4</td>
<td>1.52E-04</td>
<td>0.31 3100</td>
<td>0.17 1722</td>
</tr>
<tr>
<td>Total</td>
<td></td>
<td></td>
<td>6.9E-02</td>
<td>100.00 1000000</td>
<td>96.72 357213</td>
</tr>
</tbody>
</table>

### Leadframe

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<thead>
<tr>
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</tr>
</thead>
<tbody>
<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
<td>7440-50-5</td>
<td>3.28E-02</td>
<td>37.5% 3750000</td>
<td>36.1% 1680000</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Iron</td>
<td>7439-88-6</td>
<td>7.01E-04</td>
<td>2.35 23500</td>
<td>0.87 8705</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Zinc</td>
<td>7440-66-6</td>
<td>4.04E-05</td>
<td>0.12 1200</td>
<td>0.04 440</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Phosphorus</td>
<td>7755-14-0</td>
<td>1.01E-05</td>
<td>0.03 300</td>
<td>0.01 111</td>
</tr>
<tr>
<td>Total</td>
<td></td>
<td></td>
<td>3.37E-02</td>
<td>100.00 1000000</td>
<td>37.06 370556</td>
</tr>
</tbody>
</table>

### Internal Leadframe Plating

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Tin &amp; its alloys</td>
<td>Tin</td>
<td>7440-31-5</td>
<td>2.15E-03</td>
<td>100.00 1000000</td>
<td>2.37 23855</td>
</tr>
</tbody>
</table>

### Bond Wires

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Precious metals</td>
<td>Gold</td>
<td>7440-51-5</td>
<td>1.75E-01</td>
<td>1750 1750000</td>
<td>1.15 11527</td>
</tr>
<tr>
<td>Precious metals</td>
<td>Palladium</td>
<td>7440-03-5</td>
<td>1.06E-05</td>
<td>1000 1000000</td>
<td>0.01 116</td>
</tr>
<tr>
<td>Total</td>
<td></td>
<td></td>
<td>1.06E-05</td>
<td>100.00 1000000</td>
<td>1.16 11638</td>
</tr>
</tbody>
</table>

### Chip

<table>
<thead>
<tr>
<th>Description</th>
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<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Other inorganic materials</td>
<td>Copper (tarnished)</td>
<td></td>
<td>2.98E-03</td>
<td>100.00 1000000</td>
<td>3.15 31476</td>
</tr>
</tbody>
</table>

### Die Attach

<table>
<thead>
<tr>
<th>Description</th>
<th>Substance</th>
<th>CAS#</th>
<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Precious metals</td>
<td>Silver</td>
<td>7440-22-4</td>
<td>3.47E-04</td>
<td>73.54 7354000</td>
<td>0.38 3871</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Epoxy resin A</td>
<td>T8013</td>
<td>3.47E-05</td>
<td>7.35 735000</td>
<td>0.04 381</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Anhydride</td>
<td>T8018</td>
<td>3.47E-05</td>
<td>7.35 735000</td>
<td>0.04 381</td>
</tr>
</tbody>
</table>
| Other organic materials      | 2,6-Diisocyanatophenyl
  allyl ether oligomer     | Unassigned               |                 | 1.39E-05   | 2.94 29400                 | 0.02 153        |
| Other organic materials      | Epoxy resin B           | T8027            | 1.39E-05   | 2.94 29400                 | 0.02 153        |
| Other                      | Epoxy resin modifier    | T8028            | 1.39E-05   | 2.94 29400                 | 0.02 153        |
| Others                      | Anhydride               | T8018            | 1.39E-05   | 2.94 29400                 | 0.02 153        |
| Total                      |                         |                 | 4.72E-04   | 100.00 1000000             | 0.52 5138       |

### Package Totals

<table>
<thead>
<tr>
<th>Weight (g)</th>
<th>Percentage (%)</th>
<th>PPM</th>
</tr>
</thead>
<tbody>
<tr>
<td>9.09E-02</td>
<td>100</td>
<td>1000000</td>
</tr>
</tbody>
</table>

---

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## Product / Package Information

**Package**: LFCSP - Sawn  
**Body Size (mm)**: 6 x 6 x 0.75 (4.1 EP)  
**Lead Count**: 40  
**Terminal Finish**: NiPdAu  
**MS Number**: MS010714B

## Environmental Information

- **RoHS Compliant**: Yes  
- **High Temperature Compliant**: Yes  
- **Halogen Free Compliant**: Yes  
- **REACH SVHC Compliant**: Yes

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<tbody>
<tr>
<td>Other inorganic materials</td>
<td>SiO₂</td>
<td>8047-65-0</td>
<td>4.98E-02</td>
<td>82.89</td>
</tr>
<tr>
<td>Thermosets</td>
<td>Epoxy resin</td>
<td>Proprietary</td>
<td>2.78E-03</td>
<td>5.42</td>
</tr>
<tr>
<td>Thermosets</td>
<td>Phenol resin</td>
<td>Proprietary</td>
<td>1.77E-03</td>
<td>3.45</td>
</tr>
<tr>
<td>Other inorganic materials</td>
<td>Metal Hydride</td>
<td>Proprietary</td>
<td>2.78E-03</td>
<td>5.42</td>
</tr>
<tr>
<td>Others</td>
<td>Others</td>
<td>Proprietary</td>
<td>1.26E-03</td>
<td>2.46</td>
</tr>
</tbody>
</table>

### Leadframe

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<thead>
<tr>
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</tr>
</thead>
<tbody>
<tr>
<td>Copper &amp; its alloys</td>
<td>Copper</td>
<td>7440-00-0</td>
<td>3.54E-02</td>
<td>97.50</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Iron</td>
<td>7439-89-6</td>
<td>8.52E-04</td>
<td>2.35</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Zinc</td>
<td>7440-66-6</td>
<td>4.35E-05</td>
<td>0.12</td>
</tr>
<tr>
<td>Copper &amp; its alloys</td>
<td>Phosphorus</td>
<td>7723-14-0</td>
<td>1.09E-05</td>
<td>0.03</td>
</tr>
</tbody>
</table>

### Internal / External Leadframe Plating

<table>
<thead>
<tr>
<th>Substance</th>
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<th>Weight (g)</th>
<th>Homogeneous Material Level</th>
<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Nickel &amp; its alloys</td>
<td>Nickel</td>
<td>7440-00-0</td>
<td>3.75E-04</td>
<td>97.3</td>
</tr>
<tr>
<td>Precious metals</td>
<td>Palladium</td>
<td>7440-00-0</td>
<td>2.03E-05</td>
<td>2.3</td>
</tr>
<tr>
<td>Precious metals</td>
<td>Gold</td>
<td>7440-00-0</td>
<td>4.21E-05</td>
<td>1.5</td>
</tr>
</tbody>
</table>

### Bond Wires

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<tr>
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<th>Component Level</th>
</tr>
</thead>
<tbody>
<tr>
<td>Precious metals</td>
<td>Gold</td>
<td>7440-00-0</td>
<td>1.93E-04</td>
<td>100.9</td>
</tr>
</tbody>
</table>

### Chip

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</tr>
</thead>
<tbody>
<tr>
<td>Other inorganic materials</td>
<td>Doped Silicon</td>
<td>7440-21-3</td>
<td>1.50E-03</td>
<td>100.0</td>
</tr>
</tbody>
</table>

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<tr>
<td>Precious metals</td>
<td>Silver</td>
<td>7440-22-4</td>
<td>4.10E-04</td>
<td>77.00</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Acrylic resin</td>
<td>Proprietary</td>
<td>3.72E-05</td>
<td>7.00</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Acrylate</td>
<td>Proprietary</td>
<td>2.93E-05</td>
<td>5.50</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Polylactide derivative</td>
<td>Proprietary</td>
<td>2.39E-05</td>
<td>4.50</td>
</tr>
<tr>
<td>Thermosets</td>
<td>Epoxy resin</td>
<td>Proprietary</td>
<td>1.33E-05</td>
<td>5.42</td>
</tr>
<tr>
<td>Other organic materials</td>
<td>Butadiene Copolymer</td>
<td>Proprietary</td>
<td>7.98E-06</td>
<td>1.50</td>
</tr>
<tr>
<td>Others</td>
<td>Additive</td>
<td>Proprietary</td>
<td>7.98E-06</td>
<td>1.50</td>
</tr>
<tr>
<td>Others</td>
<td>Peroxide</td>
<td>Proprietary</td>
<td>2.66E-06</td>
<td>0.50</td>
</tr>
</tbody>
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